
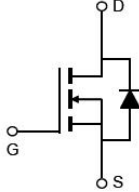


## QIAOXIN N-Channel Super Trench Power MOSFET

<p><b>Description</b></p> <p>The VCRRP02515F uses <b>Super Trench</b> technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of <math>R_{DS(on)}</math> and <math>Q_g</math>. This device is ideal for high-frequency switching and synchronous rectification.</p> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>• LED backlighting</li> <li>• Ideal for high-frequency switching and synchronous rectification</li> </ul>	<p><b>General Features</b></p> <ul style="list-style-type: none"> <li>• <math>V_{DS} = 250V, I_D = 15A</math> <math>R_{DS(on)} = 220m\Omega</math> (typical) @ <math>V_{GS} = 10V</math></li> <li>• Excellent gate charge x <math>R_{DS(on)}</math> product(FOM)</li> <li>• Very low on-resistance <math>R_{DS(on)}</math></li> <li>• 175 °C operating temperature</li> <li>• Pb-free lead plating</li> </ul>
<p>TO-220F</p>  <p>Top View</p>	 <p>Schematic Diagram</p>

### Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRRP02515F		TO-220F

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	250	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	15	A
Drain Current-Continuous( $T_C = 100^\circ C$ )	$I_D(100^\circ C)$	10.5	A
Pulsed Drain Current	$I_{DM}$	60	A
Maximum Power Dissipation	$P_D$	30	W
Derating factor		0.2	W/ $^\circ C$
Single pulse avalanche energy <sup>(Note 1)</sup>	$E_{AS}$	150	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	5	$^\circ C/W$
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### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

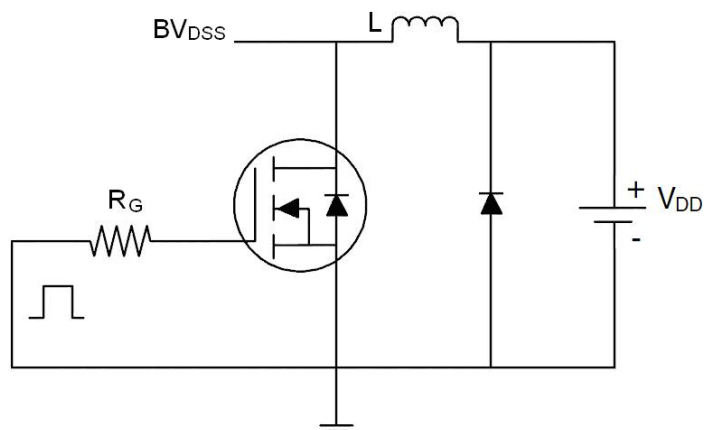
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	250	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =250V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =7.5A	-	220	250	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =7.5A	-	10	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =125V, V <sub>GS</sub> =0V, F=1.0MHz	-	500		PF
Output Capacitance	C <sub>oss</sub>		-	35.5		PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	5.5		PF
<b>Switching Characteristics</b> (Note 2)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =125V, R <sub>L</sub> =8Ω V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	18	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =125V, I <sub>D</sub> =7.5A, V <sub>GS</sub> =10V	-	11.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	3	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =15A	-	-	1.2	V
Diode Forward Current	I <sub>S</sub>		-	-	15	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub>	-	56	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt = 100A/μs	-	125	-	nC

#### Notes:

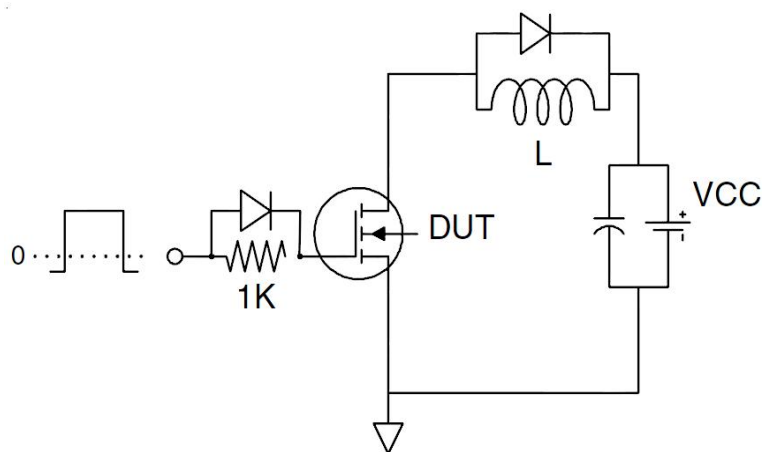
1. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=175°C. The SOA curve provides a single pulse rating.

## Test Circuit

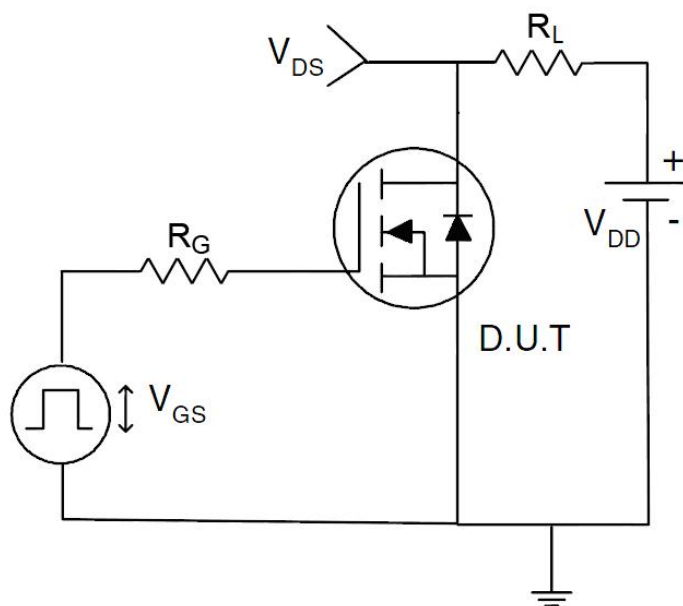
### 1) $E_{AS}$ test Circuit



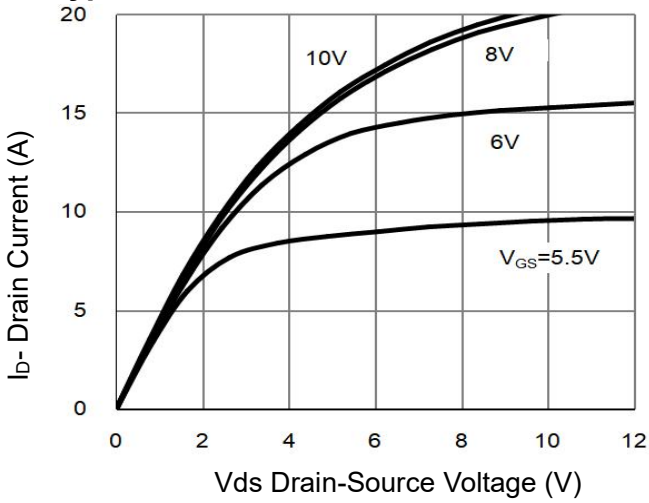
### 2) Gate charge test Circuit



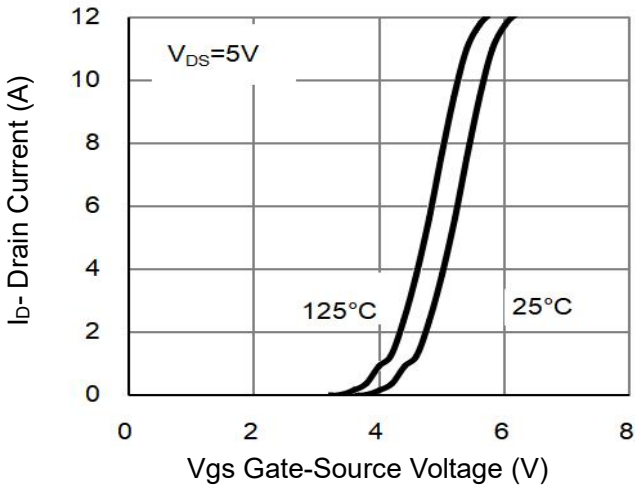
### 3) Switch Time Test Circuit



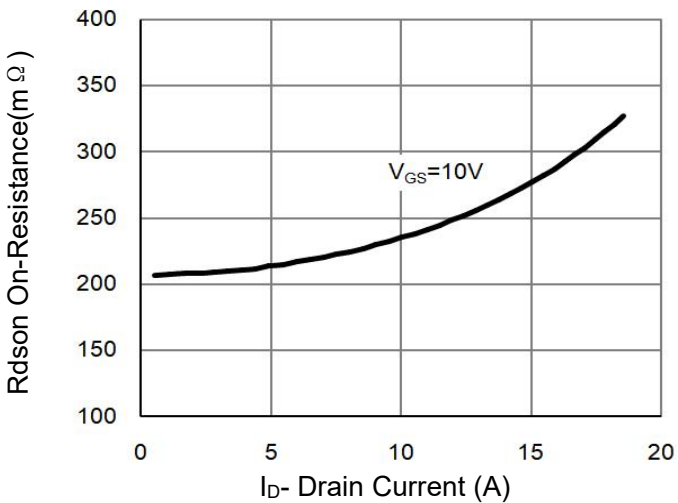
**Typical Electrical and Thermal Characteristics**



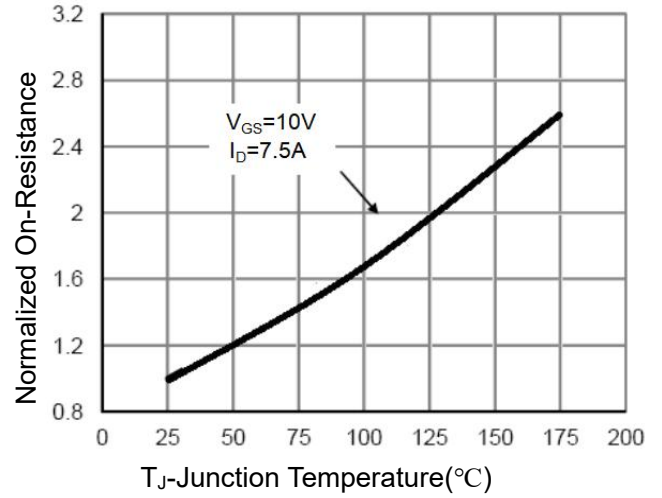
**Figure 1 Output Characteristics**



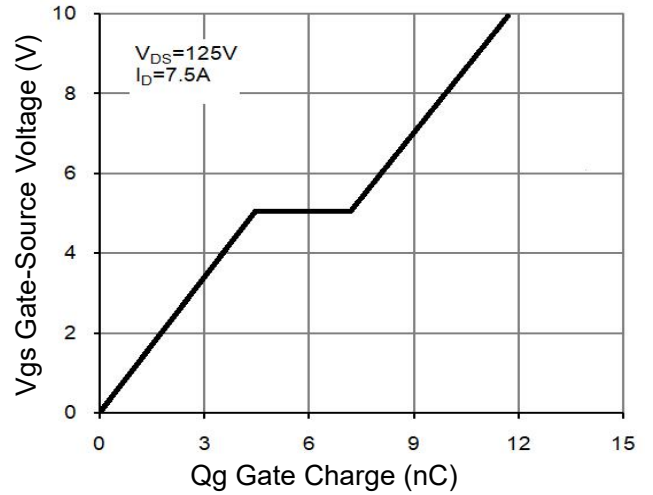
**Figure 2 Transfer Characteristics**



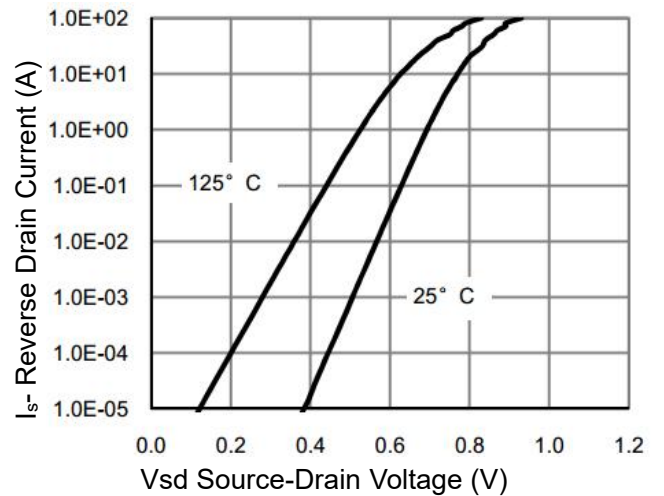
**Figure 3 Rdson- Drain Current**



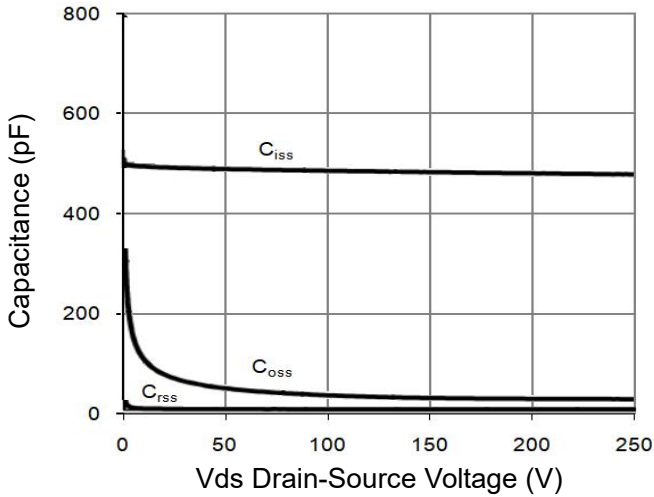
**Figure 4 Rdson-Junction Temperature**



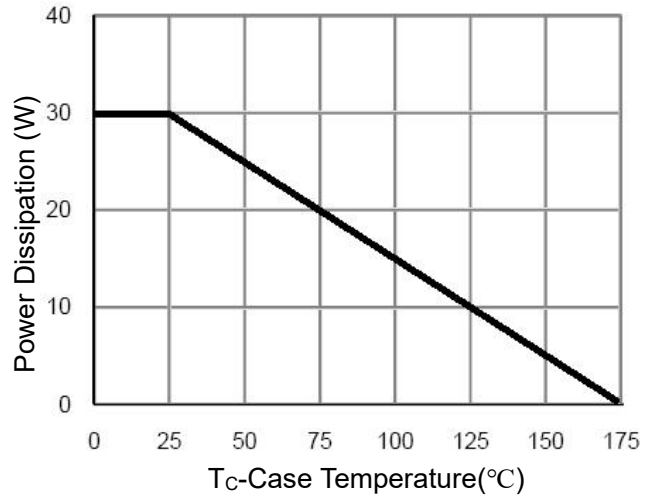
**Figure 5 Gate Charge**



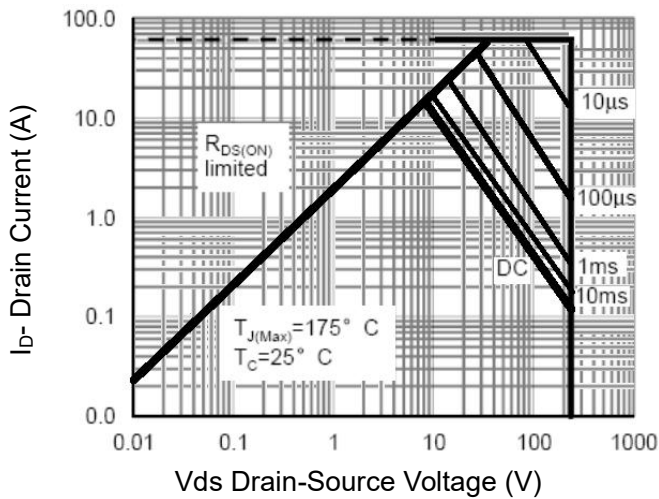
**Figure 6 Source- Drain Diode Forward**



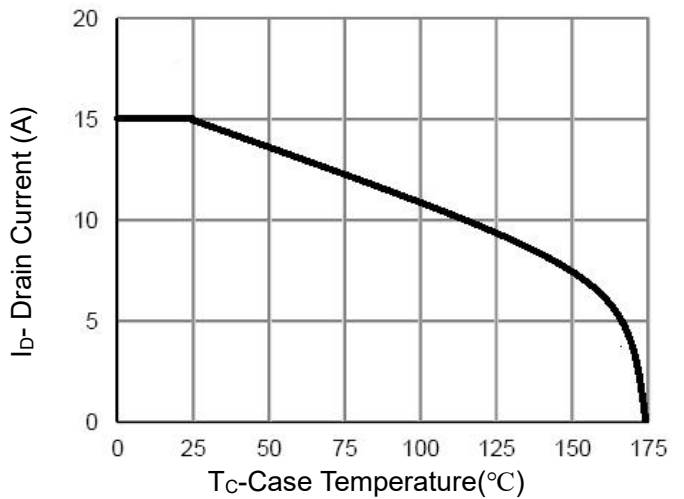
**Figure 7 Capacitance vs Vds**



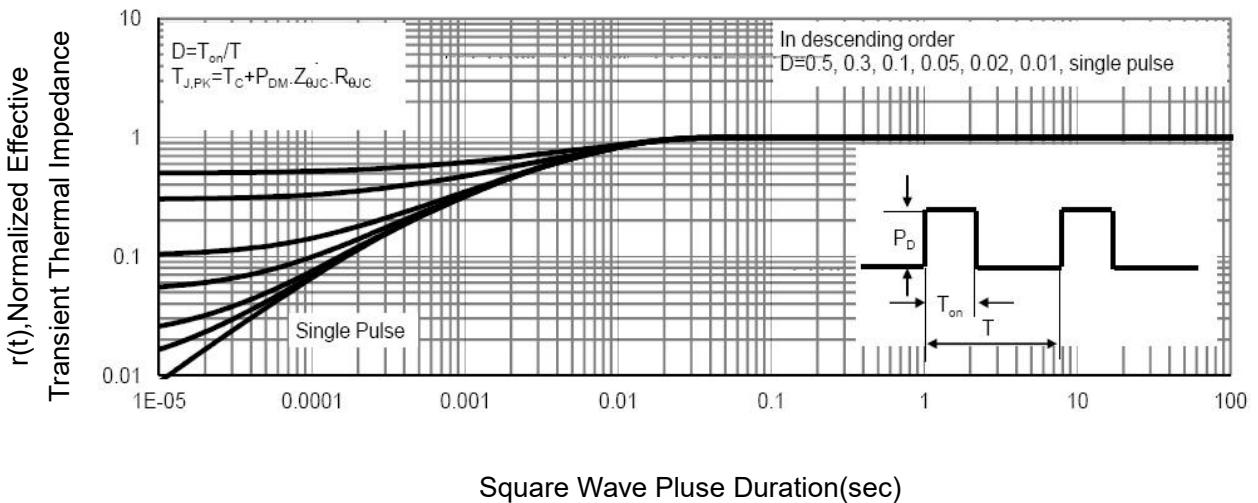
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area** (Note3)

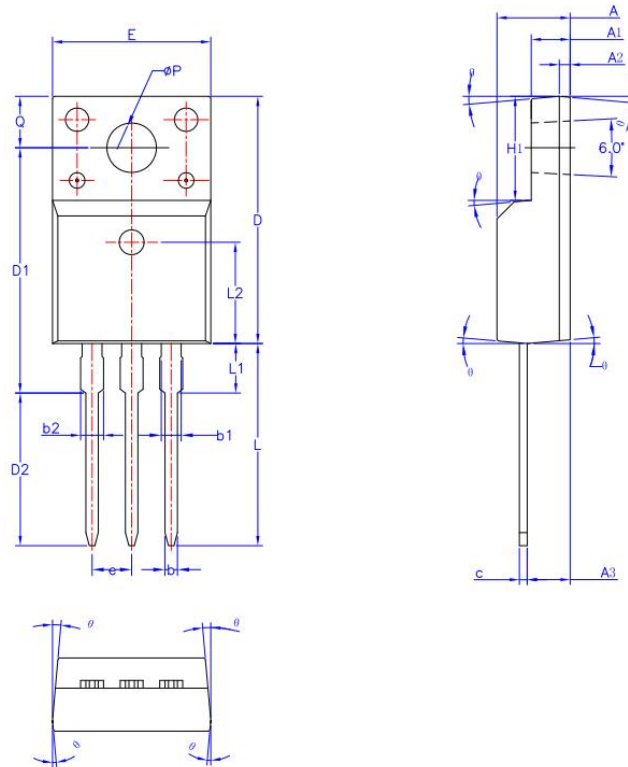


**Figure 10 Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-220F Package Information



SYMBOL	MIN	NOM	MAX
A	4.50	4.70	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.70	—	0.90
b1	1.18	—	1.38
b2	—	—	1.47
c	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	9.60	9.80	10.0
E	9.96	10.16	10.36
e	2.54BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	—	—	3.50
L2	6.50REF		
$\phi P$	3.08	3.18	3.28
Q	3.20	—	3.40
$\theta$ 1	1°	3°	5°

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### Attention

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